



## Customer Information Notification

201209004I

**Issue Date:** 15-Oct-2012

**Effective Date:** 29-Oct-2012

Dear *Product Data*,

Here's your personalized quality information concerning products Mouser Electronics purchased from NXP.

For detailed information we invite you to [view this notification online](#)



### Change Category

- |  |   |   |  |
|--|---|---|--|
| <input type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process   | <input checked="" type="checkbox"/> Product Marking     | <input type="checkbox"/> Design                    |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location  | <input type="checkbox"/> Assembly Location  | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling |

## Change of Product Marking for SOT89

### Information Notification

The Product Marking Code of SOT89 will be changed. For details please refer to the attached document.

### Why do we issue this Information Notification

Adaption to Customer requirements.

### Identification of Affected Products

Top side marking

### Impact

Only the product marking code will be changed. There is no change to all other assembly processes or the materials used. Therefore there will be no impact on the performance of the device.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

### Additional information

Additional documents: [view online](#)

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support

**e-mail address** Discr.QA.Helpdesk.GA-Products@nxp.com

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NXP Semiconductors GA GmbH  
BL General Applications PL Discretes

# *Addendum to CIN*

*Change of marking code SOT89  
(CIN 201209004I)*

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## 1. Subject

The Addendum to the Customer Information Note (CIN) 201209004I gives background information about the change of the product marking of types in SOT89 package.

## 2. Introduction

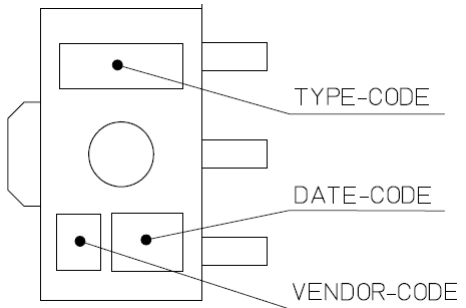
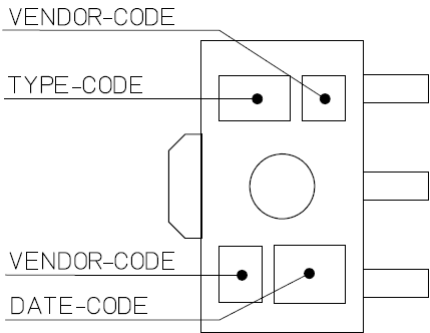
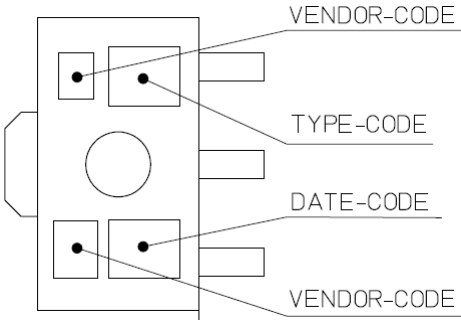
In PCN 201108004F (Transfer of Assembly line SOT89) it was announced that the marking code that was used in the assembly side NXP assembly site Hong Kong (APHK) will be changed. Due to customer demand this change will be revised, the marking code will be changed again to the appearance it had before the assembly transfer.

## 3. Material and process details

Only the marking code will be changed. The vendor code ("W" indicating NXP assembly site Guangdong (APG)) will be placed in the top row in addition to the bottom row.

The marking code will only be changed at the products stated in section 8. Products not mentioned in that section are not affected by this Information Notice.

The design of the products, the materials used and the wafer fab and assembly processes remain unchanged. The label information on the reels and boxes will remain the same.

<b>Old marking code (as announced in PCN 201108004F)</b>		
<b>New marking code</b>	<b>BFQ591</b> 	<b>All others</b> 
	<b>Vendorcode: "W" for APG</b>	

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#### 4. Reliability test program

n.a.

#### 5. Constructional details of test vehicles

n.a.

#### 6. Qualification family

n.a.

#### 7. Qualification Results

n.a.

### **Electrical and thermal performance**

#### *Electrical performance*

Full electrical characterization over temperature range has been performed. Electrical parameters remain unchanged (in specification and with the same distribution).

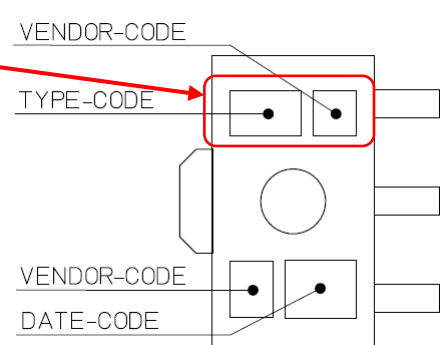
#### *Thermal performance*

Thermal parameters remain unchanged (in specification and with the same distribution).

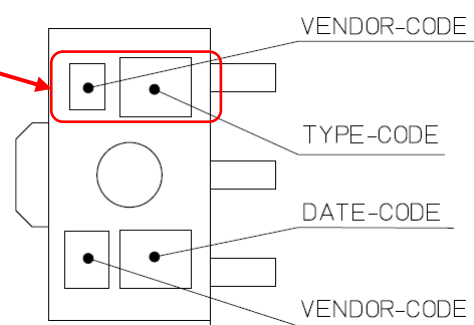
#### 8. Comparison of visual appearance

The marking code will be changed. In the table below the comparison of the old and the new marking can be found.

12NC	Type	old marking (top row)	new marking (top row)	
		Type Code	Type Code	Vendor Code
934056947115	BFQ591	BCp	BC	W



12NC	Type	old marking (top row)	new marking (top row)	
		Type Code	Vendor Code	Type Code
933821820115	PXT2222A	p1P	W	1P
933821830115	PXT2907A	p2F	W	2F
933834420115	PXTA14	p1N	W	1N
933890540115	PXT4401	p2X	W	2X
933890550115	PXT4403	p2T	W	2T
933926790115	PXTA42	p1D	W	1D
933926800115	PXTA92	p2D	W	2D
934055629115	PBSS5250X	p1L	W	1L
934055629135	PBSS5250X	p1L	W	1L
934057104135	PBSS5540X	p1G	W	1G
934057105135	PBSS4540X	p1B	W	1B
934057501135	BGA6289	p3A	W	3A
934057502135	BGA6489	p4A	W	4A
934057503135	BGA6589	p5A	W	5A
934057967115	PBSS4250X	p1M	W	1M
934057967135	PBSS4250X	p1M	W	1M
934057975135	PBSS8110X	p4B	W	4B
934057976135	PBSS9110X	p4C	W	4C
934058036115	PBSS4330X	p1R	W	1R
934058036135	PBSS4330X	p1R	W	1R
934058037115	PBSS5330X	p1S	W	1S
934058037135	PBSS5330X	p1S	W	1S
934058128135	PBSS4520X	p1F	W	1F
934058149135	PBSS5520X	p1K	W	1K
934058209135	PBSS4480X	p1Y	W	1Y
934058211135	PBSS5480X	p1Z	W	1Z
934059007115	PBSS301NX	p5B	W	5B
934059008115	PBSS302NX	p5C	W	5C
934059009115	PBSS303NX	p5D	W	5D
934059011115	PBSS304NX	p5E	W	5E
934059012115	PBSS305NX	p5F	W	5F
934059013115	PBSS306NX	p5G	W	5G
934059014115	PBSS301PX	p5H	W	5H
934059015115	PBSS302PX	p5J	W	5J
934059016115	PBSS303PX	p5K	W	5K
934059017115	PBSS304PX	p5L	W	5L
934059018115	PBSS305PX	p5M	W	5M
934059019115	PBSS306PX	p5N	W	5N
934061422115	PBHV9115X	p4G	W	4G
934063186115	BCX53-16/DG/B2	p6B	W	6B
934063402115	PBSS4021NX	p6D	W	6D
934063403115	PBSS4021PX	p6E	W	6E
934063404115	PBSS4041NX	p6F	W	6F
934063405115	PBSS4041PX	p6G	W	6G
934063406115	PBSS4032NX	p6H	W	6H
934063407115	PBSS4032PX	p6J	W	6J
934064743115	BCX53/DG/B2	p6N	W	6N



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934064821115	BCX56-16/DG/B2	p6P	W	6P
934065152135	PBSS4480X/DG	p6S	W	6S
934066534115	PBSS4021NX/WD	p6D	W	6D
935289297115	BGA7024	p6K	W	6K
935289297135	BGA7024	p6K	W	6K
935289298115	BGA7027	p6L	W	6L
935289298135	BGA7027	p6L	W	6L

## 9. Traceability

The products assembled in APG can be identified by the date code after the change. The new marking code will be introduced tentatively end of October 2012.

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## Document Revision Sheet

R E V I S I O N   S H E E T			
DATE	REV.	DESCRIPTION	AUTHOR
2012-09-13	01	New creation	Pinkernelle